

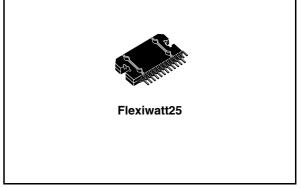
## 4 x 25W quad bridge car radio amplifier

#### **Features**

- High output power capability:
  - 4 x 30 W/4  $\Omega$  max.
  - 4 x 25 W/4  $\Omega$  EIAJ
  - 4 x 18 W/4  $\Omega$  @ 14.4 V, 1 kHz, 10 %
  - 4 x 15 W/4  $\Omega$  @ 13.2 V, 1 kHz, 10 %
- Clipping detector
- Low distortion
- Low output noise
- St-by function
- Mute function
- Automute at min. supply voltage detection
- Diagnostics facility for:
  - Clipping
  - Out to GND short
  - Out to V<sub>S</sub> short
  - Thermal shutdown
- Low external component count:
  - Internally fixed gain (26 dB)
  - No external compensation
  - No bootstrap capacitors

#### **Protections:**

- Output short circuit to GND, to V<sub>S</sub>, across the load
- Very inductive loads
- Overrating chip temperature with soft thermal limiter



- Load dump voltage
- Fortuitous open GND
- Reversed battery
- ESD protection

#### **Description**

The TDA7381 is a class AB audio power amplifier in Flexiwatt25 package designed for car radio applications. Thanks to the fully complementary PNP/NPN output configuration the TDA7381 allows a rail to rail output voltage swing with no need of bootstrap capacitors..

The extremely reduced components count allows very compact sets. The on-board clipping detector simplifies gain compression operations. The fault diagnostics makes it possible to detect mistakes during Car- Radio assembly and wiring in the car

Table 1. Device summary

Order code	Package	Packing
TDA7381	Flexiwatt25	Tube

Contents TDA7381

## **Contents**

1	Bloc	ck / application diagram and pins connection diagram	3
2	Elec	etrical specifications	4
	2.1	Absolute maximum ratings	4
	2.2	Thermal data	4
	2.3	Electrical characteristcs	4
	2.4	Printed circuit board and component layout	6
3	Арр	lication hints	7
	3.1	Biasing and SVR	7
	3.2	Input stage	7
	3.3	Stand-by and muting	7
	3.4	Diagnostics facility	8
	3.5	Stability and layout considerations	10
4	Pack	kage information	11
5	Revi	ision history	12

# 1 Block / application diagram and pins connection diagram

Figure 1. Block and application diagram

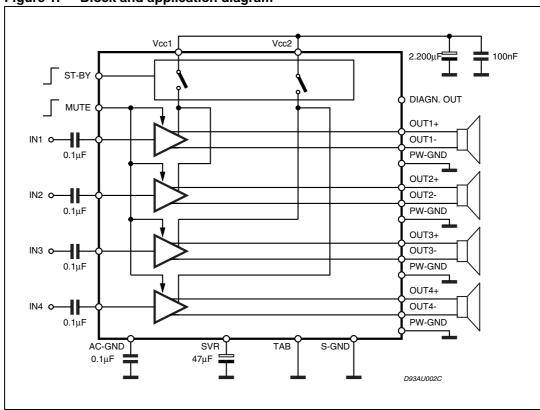
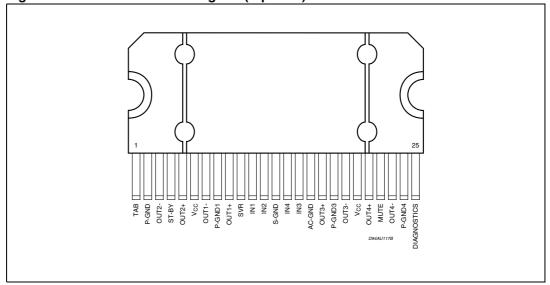


Figure 2. Pins connection diagram (top view)



## 2 Electrical specifications

## 2.1 Absolute maximum ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	Operating supply voltage	18	V	
V <sub>CC (DC</sub> )	DC supply voltage	28	V	
V <sub>CC (pk)</sub>	Peak supply voltage (t = 50 ms)	50	V	
I <sub>O</sub>	Output peak current: Repetitive (duty cycle 10 % at f = 10 Hz) Non repetitive (t = 100 $\mu$ s)	3 4	A A	
P <sub>tot</sub>	Power dissipation, (T <sub>case</sub> = 70 °C)	80	W	
Tj	Junction temperature	150	°C	
T <sub>stg</sub>	Storage temperature	-40 to 150	°C	

### 2.2 Thermal data

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R <sub>th j-case</sub>	Thermal resistance junction to case max.	1	°C/W

#### 2.3 Electrical characteristcs

#### Table 4. Electrical characteristcs

(V<sub>S</sub> = 14.4 V; f = 1 kHz; R<sub>g</sub> = 600  $\Omega$ ; R<sub>L</sub> = 4  $\Omega$ ; T<sub>amb</sub> = 25 °C; Refer to the test and application circuit (*Figure 3*), unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
I <sub>q1</sub>	Quiescent current			180	300	mA
V <sub>OS</sub>	Output offset voltage				100	mV
G <sub>v</sub>	Voltage gain		25	26	27	dB
		THD = 10 %	16.5	18		W
В	P <sub>o</sub> Output power	THD = 1 %	13	14		W
Γ <sub>0</sub>		THD = 10 %; V <sub>S</sub> = 13.2 V	13.5	15		W
		THD = 1 %; V <sub>S</sub> = 13.2 V	11	12		W
P <sub>o EIAJ</sub>	EIAJ output power (1)	EIAJ (V <sub>S</sub> = 13.7 V)	23	25		W
P <sub>o max</sub>	Max. output power (1)	V <sub>S</sub> = 13.7 V	28	30		W
THD	Distortion	P <sub>0</sub> = 4 W		0.04	0.3	%

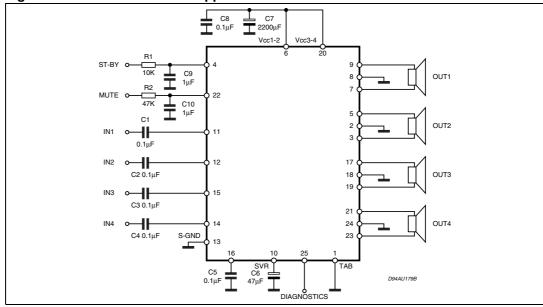
Table 4. **Electrical characteristcs (continued)** 

(V<sub>S</sub> = 14.4 V; f = 1 kHz; R<sub>g</sub> = 600  $\Omega$ ; R<sub>L</sub> = 4  $\Omega$ ; T<sub>amb</sub> = 25 °C; Refer to the test and application circuit (*Figure 3*), unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
_	Output noise	"A" Weighted		50		μV
e <sub>No</sub>	Output noise	Bw = 20 Hz to 20 kHz		65	150	μV
SVR	Supply voltage rejection	f = 100 Hz	50	65		dB
f <sub>cl</sub>	Low cut-off frequency			20		Hz
f <sub>ch</sub>	High cut-off frequency		75			KHz
R <sub>i</sub>	Input impedance		70	100		ΚΩ
C <sub>T</sub>	Cross talk	f = 1KHz	50	70		dB
I <sub>SB</sub>	St-by current consumption	St-by = LOW			100	μΑ
V <sub>SB out</sub>	St-by out threshold voltage	(Amp: ON)	3.5			V
V <sub>SB IN</sub>	St-by in threshold voltage	(Amp: OFF)			1.5	V
A <sub>M</sub>	Mute attenuation	V <sub>O</sub> = 1 Vrms	80	90		dB
V <sub>M out</sub>	Mute out threshold voltage	(Amp: play)	3.5			V
$V_{M in}$	Mute in threshold voltage	(Amp: mute)			1.5	V
I <sub>m (L)</sub>	Muting pin current	V <sub>MUTE</sub> = 1.5 V; (source current)	5	10	16	μΑ
I <sub>CDOFF</sub>	Clipping detector "OFF" output average current	THD = 1 % <sup>(2)</sup>		100		μΑ
I <sub>CDON</sub>	Clipping Detector "ON" Output Average Current	THD = 10 % <sup>(2)</sup>	100	240	350	μΑ

- 1. Saturated square wave output.
- 2. Diagnostics output pulled-up to 5 V with 10  $k\Omega$  series resistor.

Figure 3. Standard test and application circuit



**577** 

## 2.4 Printed circuit board and component layout

Figure 4. Components and top copper layer of the Figure 3

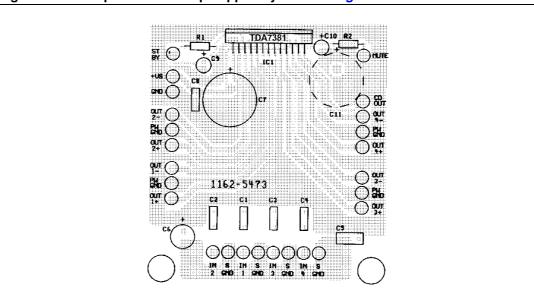
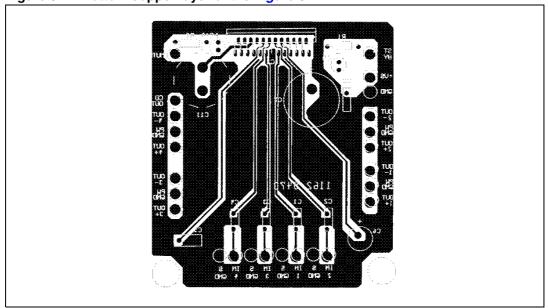


Figure 5. Bottom copper layer of the Figure 3



TDA7381 Application hints

## 3 Application hints

#### 3.1 Biasing and SVR

As shown by *Figure 3*, all the TDA7381's main sections, such as Inputs, Outputs and AC-GND (pin 16) are internally biased at half supply voltage level (Vs/2), which is derived from the supply voltage rejection (SVR) block. In this way no current flows through the internal feedback network.

The AC-GND is common to all the 4 amplifiers and represents the connection point of all the inverting inputs. Both individual inputs and AC-GND are connected to Vs/2 (SVR) by means of 100  $k\Omega$  resistors.

To ensure proper operation and high supply voltage rejection, it is of fundamental importance to provide a good impedance matching between INPUTS and AC-GROUND terminations.

This implies that  $C_1$ ,  $C_2$ ,  $C_3$ ,  $C_4$ ,  $C_5$  capacitors have to carry the same nominal value and their tolerance should never exceed  $\pm 10$  %.

Besides its contribution to the ripple rejection, the SVR capacitor governs the turn ON/OFF time sequence and, consequently, plays an essential role in the pop optimization during ON/OFF transients. To conveniently serve both needs, **its minimum recommended value is 10**  $\mu$ F.

#### 3.2 Input stage

The TDA7381'S inputs are ground-compatible and can stand very high input signals ( $\pm$  8 Vpk) without any performances degradation. If the standard value for the input capacitors (0.1  $\mu$ F) is adopted, the low frequency cut-off will amount to 16 Hz.

## 3.3 Stand-by and muting

Stand-by and muting facilities are both CMOS-compatible. If unused, a straight connection to Vs of their respective pins would be admissible.

Conventional low-power transistors can be employed to drive muting and stand-by pins in absence of true CMOS ports or microprocessors. R-C cells have always to be used in order to smooth down the transitions for preventing any audible transient noises. Since a DC current of about 10  $\mu A$  normally flows out of pin 22, the maximum allowable muting-series resistance (R2) is 70 kΩ, which is sufficiently high to permit a muting capacitor reasonably small (about  $1\mu F$ ). If R2 is higher than recommended, the involved risk will be that the voltage at pin 22 may rise to above the 1.5 V threshold voltage and the device will consequently fail to turn OFF when the mute line is brought down.

About the stand-by, the time constant to be assigned in order to obtain a virtually pop-free transition has to be slower than 2.5 V/ms.

5/

Application hints TDA7381

## 3.4 Diagnostics facility

The TDA7381 is equipped with a diagnostics circuitry able to detect the following events:

- Clipping in the output stage
- Overheating (thermal shut-down proximity)
- Output misconnections (OUT-GND and OUT-Vs shorts)

Diagnostics information is available across an open collector output located at pin 25 (fig. 8) through a current sinking whenever at least one of the above events is recognized.

Among them, the **Clipping detector** acts in a way to output a signal as soon as one or more power transistors start being saturated.

As a result, the clipping-related signal at pin 25 takes the form of pulses, which are perfectly syncronized with each single clipping event in the music program and reflect the same duration time (*Figure 8*).

Applications making use of this facility usually operate a filtering/integration of the pulses train through passive R-C networks and realize a volume (or tone bass) stepping down in association with microprocessor-driven audioprocessors.

The maximum load that pin 25 can sustain is 1 k $\Omega$ . Due to its operating principles, the clipping detector has to be viewed mainly as a power-dependent feature rather than frequency-dependent. This means that clipping state will be immediately signaled out whenever a fixed power level is reached, regardless of the audio frequency.

Figure 6. Input/output biasing.

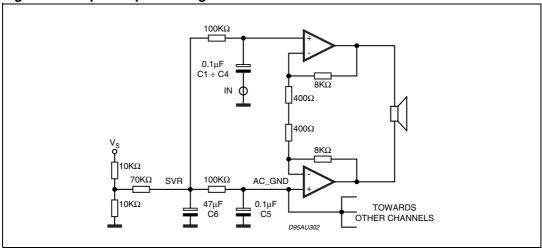
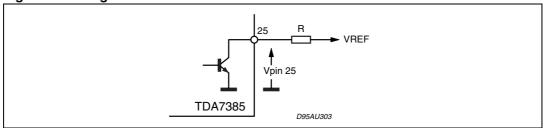


Figure 7. Diagnostics circuit



**TDA7381 Application hints** 

Uп AUDID BUTPUT SIGNAL CLIPPING ICLIP DET OUTPUT CURR. ø M91TDA7368-84

Figure 8. Clipping detection waveforms.

In other words, this feature offers the means to counteract the extremely sound-damaging effects of clipping, caused by a sudden increase of odd order harmonics and appearance of serious intermodulation phenomena. Another possible kind of distortion control could be the setting of a maximum allowable THD limit (e.g. 0.5%) over the entire audio frequency range. Besides offering no practical advantages, this procedure cannot be much accurate, as the non-clipping distortion is likely to vary over frequency.

In case of **overheating**, pin 25 will signal out the junction temperature proximity to the thermal shut-down threshold. This will typically start about 2°C before the thermal shutdown threshold is reached.

As various kind of diagnostics information is available at pin 25 (clipping, shorts and overheating), it may be necessary to operate some distinctions on order to treat each event separately.

This could be achieved by taking into account the intrinsically different timing of the diagnostics output under each circumstance. In fact, clipping will produce pulses normally much shorter than those present under faulty conditions.

An example of circuit able to distinguish between the two occurrences is shown by Figure 10.

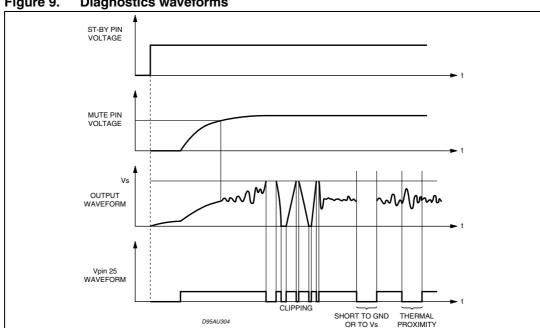


Figure 9. **Diagnostics waveforms** 

Application hints TDA7381

### 3.5 Stability and layout considerations

If properly layouted and hooked to standard carradio speakers, the TDA7381 will be intrinsically stable with no need of external compensations such as output R-C cells. Due to the high number of channels involved, this translates into a very remarkable components saving if compared to similar devices on the market.

To simplify pc-board layout designs, each amplifier stage has its own power ground externally accessible (pins 2,8,18,24) and one supply voltage pin for each couple of them.

Even more important, this makes it possible to achieve the highest possible degree of separation among the channels, with remarkable benefits in terms of cross-talk and distortion features.

About the layout grounding, it is particularly important to connect the AC-GND capacitor ( $C_5$ ) to the signal GND, as close as possible to the audio inputs ground: this will guarantee high rejection of any common mode spurious signals.

The SVR capacitor  $(C_6)$  has also to be connected to the signal GND. Supply filtering elements  $(C_7, C_8)$  have naturally to be connected to the power-ground and located as close as possible to the Vs pins.

Pin 1, which is mechanically attached to the device's tab, needs to be tied to the cleanest power ground point in the pc-board, which is generally near the supply filtering capacitors.

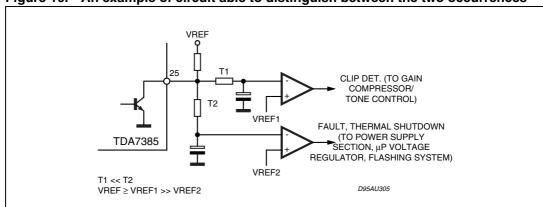


Figure 10. An example of circuit able to distinguish between the two occurrences

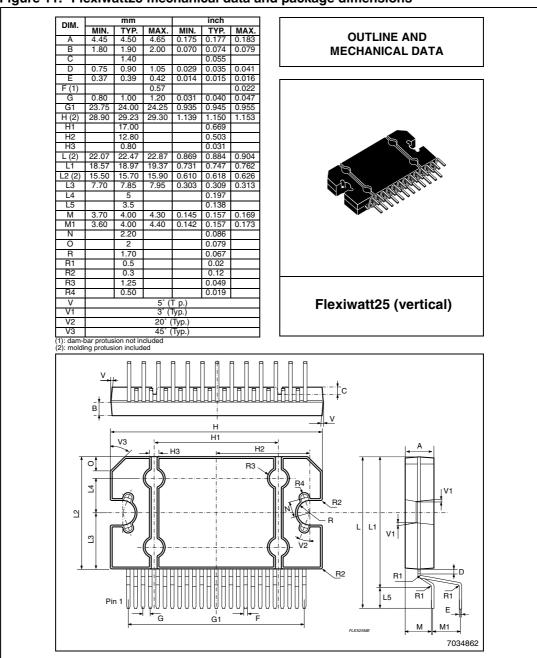
TDA7381 Package information

## 4 Package information

In order to meet environmental requirements, ST (also) offers these devices in ECOPACK<sup>®</sup> packages. ECOPACK<sup>®</sup> packages are lead-free. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Figure 11. Flexiwatt25 mechanical data and package dimensions



**577** 

Revision history TDA7381

# 5 Revision history

Table 5. Document revision history

Date	Revision	Changes
12-Oct-1999	ct-1999 5 Initial release.	
27-Jun-2008	6	Document reformatted.  Document promoted from preliminary data to datasheet.  Added <i>Table 1: Device summary</i> .  Added ECOPACK description in <i>Section 4: Package information</i> .

#### Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2008 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

